

What is claimed is:

1. A method for packaging a semiconductor device, comprising the steps of:

- 5 (a) forming an Au bump on a bond pad of a wafer;
- (b) dicing the wafer into a chip;
- (c) attaching the chip to a substrate to form a flip-chip bonding by using a thermo-pressure process;
- (d) encapsulating the flip-chip bonding by using a
- 10 nonconductive epoxy; and
- (e) sawing the substrate to singulate individual packages.

2. The method of claim 1, wherein, in the step (c), the
15 Au bump is connected to the substrate through an Ag layer
 and a Cu layer.